Listing of Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claims 1-28. (Canceled).

29. (New) An integrated circuit package, comprising:

a lead frame assembly including a central support member and a plurality of conductive leads, wherein the central support member has opposing first and second major surfaces, and wherein the plurality of conductive leads are radially disposed about the periphery of the central support member;

an integrated circuit die coupled to the first surface of the central support member and having a plurality of bond pads;

a power cell coupled to the second surface of the central support member and comprising a cathode layer, an anode layer, and a separator layer interposing the cathode and anode layers, wherein the cathode layer is doped with a first impurity type and the anode layer is doped with a second, opposite impurity type, and wherein the first and second impurity types are selected from an n-type impurity and a p-type impurity;

an electrode including a planar body and a terminal extending from the body, wherein the body is coupled to the power cell opposite the central support member;

a plurality of first wire bonds each coupling one of the plurality of bond pads and one of the plurality of conductive leads; and

a second wire bond having a first terminus coupled to one of the plurality of bond pads and a second terminus coupled to the terminal of the electrode, wherein the terminal has an arcuate shape configured to position the second terminus of the second wire bond in a reference plane that is coincident with the first surface of the central support member.

30. (New) The package of claim 29 wherein the cathode layer includes manganese dioxide doped with the first impurity type, the separator layer includes lithium perchlorate, and the anode layer includes lithium doped with the second impurity type.

31. (New) The package of claim 29 further comprising a laminated insulating layer substantially covering surfaces of the body and the terminal that are opposite the power cell.

32. (New) The package of claim 31 wherein the insulating layer comprises one of a paper material and a polyester film material.

33. (New) The package of claim 29 wherein the body and the terminal each comprise at least one of copper and nickel.

34. (New) The package of claim 29 further comprising an electrical conduction enhancement material coating at least a portion of the electrode, wherein the electrical conduction enhancement material comprises graphite.

35. (New) The package of claim 34 wherein the electrical conduction enhancement material is one of a graphite based, air-curable material and a graphite based, heat-curable material.

36. (New) The package of claim 29 further comprising an insulating layer encapsulating the central support member, the integrated circuit die, the power cell, the electrode, the plurality of first wire bonds, and the second wire bond, collectively.

37. (New) The package of claim 29 wherein the power cell further comprises a frame adjacent and extending along the perimeter of each of the cathode layer, the anode layer, and the separator layer, wherein the frame substantially comprises an insulating material.

38. (New) The package of claim 29 wherein the power cell further comprises a frame adjacent and extending along the perimeter of each of the cathode layer, the anode layer, and the separator layer, wherein the frame is open at opposing first and second ends, the first end exposing the anode layer, and the second end exposing the cathode layer.

39. (New) An integrated circuit package, comprising:

a lead frame assembly including a central support member and a plurality of conductive leads, wherein the central support member has opposing first and second major surfaces, and wherein the plurality of conductive leads are radially disposed about the periphery of the central support member;

an integrated circuit die coupled to the first surface of the central support member and having a plurality of bond pads;

an electrode including a planar body and a terminal extending from the body;

a power cell interposing the body and the integrated circuit die and coupled directly to at least one of the integrated circuit die and the body;

a plurality of first wire bonds each coupling one of the plurality of bond pads and one of the plurality of conductive leads;

a second wire bond having a first terminus coupled to one of the plurality of bond pads and a second terminus coupled to the terminal of the electrode, wherein the terminal has an arcuate shape configured to position the second terminus of the second wire bond in a reference plane that is coincident with the first surface of the central support member; and

an insulating layer encapsulating the central support member, the integrated circuit die, the electrode, the power cell, the plurality of first wire bonds, and the second wire bond, collectively.

40. (New) The package of claim 39 wherein:

the integrated circuit die includes one of an n-type semiconductor device substrate and a p-type semiconductor device substrate;

the power cell is a solid state power cell having a cathode layer, an anode layer, and a separator layer interposing the cathode and anode layers;

the anode layer interposes the cathode layer and the integrated circuit die when the integrated circuit die includes the n-type semiconductor device substrate; and

the cathode layer interposes the anode layer and the integrated circuit die when the integrated circuit die includes the p-type semiconductor device substrate.

41. (New) The package of claim 39 wherein the body has a first thickness and the power cell has a second thickness, wherein the terminal extends from the body in a perpendicular direction, relative to the reference plane, to a distance that is not substantially less than the sum of the first and second thicknesses.

42. (New) The package of claim 39 wherein the integrated circuit die, the body, and the power cell each have substantially similar footprints.

43. (New) The package of claim 39 wherein the power cell comprises a cathode layer, an anode layer, and a separator layer interposing the cathode and anode layers, wherein the cathode layer is doped with a first impurity type and the anode layer is doped with a second, opposite impurity type, and wherein the first and second impurity types are selected from an n-type impurity and a p-type impurity.

44. (New) The package of claim 39 wherein the electrode includes a coating of electrical conduction enhancing material, and wherein the power cell is coupled directly to the coating.

45. (New) An integrated circuit package, comprising:

a lead frame assembly including a central support member (CSM) having opposing first and second CSM surfaces;

an integrated circuit die (ICD) having opposing first and second ICD surfaces, wherein the first ICD surface is coupled directly to the first CSM surface;

a laminated, solid state power cell having a cathode layer implanted with a first impurity type, an anode layer implanted with a second impurity type that is opposite the first impurity type, and a separator layer interposing the cathode and anode layers, wherein a first one of the cathode and anode layers is coupled directly to the second CSM surface;

an electrode having a substantially planar body and a terminal extending from the body, wherein the electrode body is coupled directly to a second one of the cathode and anode layers;

a wire bond having first and second ends, wherein the first end is coupled directly to a bond pad located on the second ICD surface, and wherein the second end is coupled directly to the electrode terminal in a reference plane that is coincident with the first CSM surface; and

an insulating layer encapsulating the CSM, the ICD, the power cell, the electrode, and the wire bond, collectively.

46. (New) The package of claim 45 wherein the ICD, the power cell and the body each have substantially similar footprints.

47. (New) The package of claim 45 further comprising a insulating laminate substantially covering surfaces of the body and the terminal that are opposite the power cell, wherein the insulating laminate comprises at least one of a paper material and a polyester material, and wherein the encapsulating insulating layer further encapsulates the insulating laminate.

48. (New) The package of claim 45 wherein the body has a first thickness and the power cell has a second thickness, wherein the terminal extends from the body in a perpendicular direction, relative to the reference plane, to a distance that is not substantially less than the sum of the first and second thicknesses.